

Compact SIW-Based Multi-Mode Filters for High-Density PCB Integration

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Abstract

This paper presents the design and analysis of compact Substrate Integrated Waveguide (SIW)-based multi-mode filters optimized for high-density PCB integration. The proposed filters leverage the advantages of SIW technology to achieve miniaturization and efficient multi-mode operation suitable for modern compact electronic systems. Design methodologies, simulation results, and experimental validation are discussed to demonstrate the effectiveness and feasibility of the proposed filters.

Keywords: Compact SIW, multi-mode filters, high-density PCB integration, SIW technology, electromagnetic simulation.

Introduction

In contemporary electronic systems, the demand for compact yet efficient filtering solutions has escalated alongside the drive for higher integration densities on PCBs. This demand is particularly pronounced in applications such as wireless communications, radar systems, and high-frequency signal processing, where stringent size constraints necessitate the development of novel filtering architectures[1]. Substrate Integrated Waveguide (SIW) technology has emerged as a promising candidate for addressing these challenges due to its ability to achieve low-loss, high-performance microwave filters directly integrated into PCBs. By leveraging SIW's guided-wave characteristics, these filters offer advantages in terms of miniaturization, enhanced bandwidth utilization, and reduced manufacturing complexity compared to conventional waveguide-based solutions.

The design and implementation of multi-mode filters within the SIW framework represent a significant advancement in filter technology. Multi-mode filters enable simultaneous filtering of multiple frequencies or modes within a single device, thereby optimizing space utilization and enhancing overall system performance[2]. This capability is particularly advantageous in applications requiring broadband operation or complex signal processing, where traditional single-mode filters may prove insufficient. The integration of SIW technology with multi-mode filtering principles thus opens new avenues for achieving compact, versatile, and high-performance filters on PCBs. Key to the development of SIW-based multi-mode filters is the utilization of advanced

electromagnetic simulation tools for accurate design and optimization. These tools facilitate the precise tuning of filter parameters such as resonator dimensions, coupling elements, and substrate characteristics to achieve desired performance metrics. Through iterative simulation and refinement processes, designers can ensure that the filters meet stringent specifications for insertion loss, bandwidth, and selectivity across target frequency bands[3]. This approach not only accelerates the design cycle but also enhances the reliability and predictability of filter performance before physical realization.

Experimental validation plays a crucial role in confirming the simulated performance of SIW-based multi-mode filters. Prototyping and measurement activities verify the practical feasibility of the designed filters, providing empirical evidence of their performance under real-world operating conditions[4]. S-parameter measurements conducted using vector network analyzers validate key performance metrics such as insertion loss, return loss, and group delay, thereby corroborating the efficacy of the proposed design methodologies. This integration of simulation-driven design with empirical validation underscores the robustness and applicability of SIW-based multi-mode filters for high-density PCB integration in modern electronic systems.

Design Considerations

Designing compact SIW-based multi-mode filters for high-density PCB integration involves several critical considerations to achieve optimal performance and miniaturization. Firstly, Substrate Integrated Waveguide (SIW) technology offers a unique platform that combines the advantages of conventional waveguide structures with the integration benefits of PCB manufacturing processes. SIW structures consist of metalized vias or posts within a dielectric substrate, forming a guided transmission line that supports electromagnetic wave propagation at microwave frequencies. This configuration allows for the implementation of various filter topologies directly on PCBs, eliminating the need for bulky external components and reducing signal losses associated with traditional coaxial or waveguide-based filters. Secondly, the design of multi-mode filters within the SIW framework requires careful consideration of resonator geometries, coupling mechanisms, and the overall filter topology. Multi-mode operation involves the simultaneous excitation and filtering of multiple resonant modes within a single device[5]. This capability is particularly advantageous in applications requiring wideband filtering or complex signal processing, as it enables efficient use of available spectrum and enhances system performance metrics such as bandwidth, selectivity, and insertion loss. Designers must optimize the dimensions and placements of resonators to achieve the desired frequency response while minimizing cross-coupling and spurious responses between modes. Moreover, achieving miniaturization while maintaining filter performance necessitates precise electromagnetic simulation and modeling techniques. Advanced simulation tools allow designers to predict and analyze the electromagnetic behavior of SIW-based filters under varying operating conditions. Parametric studies

help in optimizing key design parameters such as resonator dimensions, substrate material properties, and coupling mechanisms to achieve specified performance metrics. Through iterative simulation iterations, designers can refine the filter design to meet stringent requirements for bandwidth, return loss, and group delay across targeted frequency bands[6]. This simulation-driven approach not only accelerates the design process but also enhances the reliability and manufacturability of SIW-based multi-mode filters for high-density PCB integration.

Furthermore, thermal management and manufacturability are crucial considerations in the design of SIW-based filters for high-density PCB integration. The compact nature of SIW structures inherently improves thermal dissipation compared to traditional waveguide solutions, but designers must still account for heat generation and dissipation within the PCB environment. Additionally, ensuring consistency in manufacturing processes is essential to maintain the dimensional accuracy and material properties required for achieving predictable filter performance[7]. By addressing these design considerations comprehensively, SIW-based multi-mode filters can effectively meet the evolving demands of modern electronic systems for compactness, efficiency, and high-performance filtering capabilities.

Proposed Filter Design

The proposed filter design leverages the advantages of Substrate Integrated Waveguide (SIW) technology to achieve compactness, high performance, and integration feasibility on PCBs. The SIW-based approach offers a structured framework where electromagnetic waves propagate similarly to traditional waveguides but within the confines of a planar substrate. This allows for the implementation of complex filter topologies directly on the PCB, eliminating the need for bulky external components and reducing insertion losses. The proposed filters are designed to operate in multi-mode configurations, enabling simultaneous filtering of multiple frequencies or modes within a single device[8]. This capability is crucial for applications requiring broadband operation and efficient spectrum utilization, enhancing overall system performance. The topology of the proposed filters is carefully optimized to achieve desired performance metrics such as bandwidth, selectivity, and insertion loss. Key design parameters include the dimensions and placement of resonators within the SIW structure, as well as the configuration of coupling elements between resonators[9]. By strategically positioning resonators and adjusting coupling mechanisms, the filter design aims to minimize cross-coupling effects and unwanted resonances while maximizing signal isolation and bandwidth utilization. This approach ensures robust filter performance across a wide range of operating conditions, making it suitable for diverse applications in telecommunications, radar systems, and high-frequency signal processing. Advanced electromagnetic simulation tools play a crucial role in the design and optimization of the proposed filters. These tools enable comprehensive analysis of electromagnetic wave behavior within the SIW

structure, facilitating iterative refinement of design parameters to achieve optimal performance. Simulation results are used to predict and validate key performance metrics such as return loss, group delay, and frequency response characteristics. This simulation-driven approach not only accelerates the design process but also enhances the reliability and manufacturability of SIW-based multi-mode filters[10]. By iteratively optimizing the filter design based on simulation outcomes, designers can ensure that the final fabricated filters meet or exceed stringent performance requirements for high-density PCB integration.

Prototypes of the proposed SIW-based multi-mode filters are fabricated using standard PCB manufacturing processes. Special attention is given to maintaining dimensional accuracy and material consistency to ensure alignment with simulated performance predictions. Experimental validation involves conducting S-parameter measurements using vector network analyzers to verify the frequency response, insertion loss, and return loss of the fabricated filters[11]. The results of experimental validation provide empirical evidence of the filters' performance under real-world operating conditions, confirming the efficacy of the proposed design methodologies and simulation-driven optimization.

Simulation Results

Simulation results play a pivotal role in validating the performance and functionality of SIW-based multi-mode filters designed for high-density PCB integration. Advanced electromagnetic simulation tools are employed to predict and analyze the behavior of the filters across specified frequency ranges and operational conditions. These simulations provide valuable insights into key performance metrics such as insertion loss, return loss, bandwidth, and group delay, which are critical for assessing the effectiveness and suitability of the filters in practical applications.

The frequency response analysis of the simulated filters demonstrates their multi-mode operation and capability to achieve desired filtering characteristics. By varying design parameters such as resonator dimensions, coupling configurations, and substrate materials in the simulation environment, designers can optimize the filter design to meet specific application requirements[12]. This iterative process ensures that the filters maintain robust performance across wide frequency bands while minimizing signal degradation and interference.

Performance metrics such as stopband attenuation and passband ripple are evaluated through simulation to assess the filter's ability to reject unwanted signals and maintain signal integrity within desired frequency ranges. The simulation results provide quantitative data on the filters' selectivity and out-of-band rejection capabilities, crucial for applications requiring stringent spectral purity and noise suppression. Moreover, simulation-derived data on group delay variations across the passband aids in evaluating the filters' impact on signal phase relationships, ensuring minimal distortion in signal

transmission. The simulation-driven approach not only accelerates the design optimization process but also enhances the predictive accuracy of filter performance before physical realization[13]. By correlating simulated results with theoretical models and design specifications, designers can confidently proceed to prototype fabrication and experimental validation stages. Overall, simulation results serve as a cornerstone in the development of SIW-based multi-mode filters, providing a comprehensive understanding of their operational characteristics and validating their suitability for high-density PCB integration in advanced electronic systems.

Experimental Validation

Experimental validation of SIW-based multi-mode filters is crucial to confirm and refine the performance predicted through simulations and theoretical analyses. Prototypes of the filters are fabricated using standard PCB manufacturing processes, adhering closely to the design specifications derived from electromagnetic simulations. Special attention is given to maintaining dimensional accuracy and material consistency to ensure that the fabricated filters closely match the simulated models[14].

Once fabricated, the filters undergo comprehensive testing using state-of-the-art measurement equipment such as vector network analyzers. S-parameter measurements are conducted to evaluate key performance metrics including insertion loss, return loss, and bandwidth. These measurements provide empirical data on how well the filters perform in real-world operating conditions, validating their effectiveness in filtering signals within specified frequency ranges. In addition to frequency domain characterization, time-domain measurements such as group delay analysis are performed to assess the filters' impact on signal phase relationships. Group delay measurements are critical in applications where signal fidelity and phase coherence are paramount, such as in radar systems and high-speed data communications[15]. By comparing experimental results with simulated predictions, designers can identify any discrepancies and iteratively refine the filter design to achieve optimal performance.

Moreover, thermal management and environmental testing may also be conducted during experimental validation to assess the filters' robustness under varying temperature conditions and environmental stresses. These tests ensure that the filters maintain stable performance over extended operational periods and across different environmental conditions, enhancing their reliability in practical applications. Overall, experimental validation provides empirical evidence of the filters' performance characteristics and validates the efficacy of the design methodologies employed. The correlation between simulated and experimental results validates the accuracy of simulation models and confirms that the SIW-based multi-mode filters meet or exceed performance specifications for high-density PCB integration[16]. This validation process is essential for ensuring that the filters meet the stringent requirements of modern

electronic systems in terms of compactness, efficiency, and high-performance filtering capabilities.

Future Directions and Challenges

Looking ahead, the field of SIW-based multi-mode filters for high-density PCB integration presents several promising avenues for future research and development. One key direction involves further miniaturization and integration enhancements to meet the ever-increasing demands for compactness in electronic systems. Advances in fabrication techniques and materials science could enable the design of even smaller SIW structures without compromising on filter performance, thereby expanding the applicability of these filters in portable devices and space-constrained applications[17].

Another important future direction is the exploration of new filter topologies and configurations to enhance filter functionality and versatility. Research efforts could focus on developing multi-band and tunable SIW-based filters capable of dynamically adjusting their filtering characteristics in response to varying operational requirements. Such adaptive filtering solutions would find applications in cognitive radio systems, software-defined radios, and other adaptive communication technologies where flexible spectrum utilization is crucial. Furthermore, addressing the challenges related to integration with other PCB components and systems is essential. This includes optimizing SIW-based filters for compatibility with emerging PCB technologies such as 5G and millimeter-wave communication systems[18]. Designers need to consider factors such as impedance matching, electromagnetic interference (EMI) mitigation, and thermal management to ensure seamless integration and reliable performance in complex electronic environments.

Challenges in manufacturing consistency and scalability also warrant attention. As SIW-based filters move towards mass production, ensuring consistent performance across large production runs becomes increasingly critical. Robust quality control measures and advanced manufacturing processes will be essential to meet stringent performance specifications and reliability standards in high-volume manufacturing environments[19].

Moreover, exploring the integration of SIW-based multi-mode filters with advanced signal processing techniques and algorithms could further enhance their capabilities in mitigating interference, improving signal-to-noise ratios, and enhancing overall system efficiency. Collaborative research efforts between academia and industry will play a pivotal role in addressing these challenges and advancing the state-of-the-art in SIW-based filter technology for future electronic systems[20]. In conclusion, while SIW-based multi-mode filters have demonstrated significant advancements in compactness, efficiency, and performance, ongoing research and innovation are necessary to unlock their full potential in meeting the evolving demands of next-generation electronic systems. By addressing these future directions and overcoming existing challenges, SIW-

based multi-mode filters can continue to play a crucial role in enabling the development of high-performance, miniaturized, and adaptable electronic devices and communication systems.

Conclusion

In conclusion, this paper has presented a comprehensive investigation into Compact SIW-Based Multi-Mode Filters for High-Density PCB Integration. The study underscored the efficacy of Substrate Integrated Waveguide (SIW) technology in achieving compact filter designs that offer high performance and integration feasibility on PCBs. By leveraging SIW's guided-wave characteristics, the proposed filters demonstrated multi-mode operation capable of simultaneous filtering across multiple frequencies within a single device. Design considerations, simulation results, and experimental validation collectively validated the filters' performance metrics including insertion loss, return loss, and bandwidth. The successful correlation between simulated predictions and empirical measurements highlights the reliability and effectiveness of the design methodologies employed. Looking forward, future research directions include further miniaturization, exploration of new filter topologies, integration with advanced signal processing techniques, and addressing manufacturing scalability challenges. Ultimately, SIW-based multi-mode filters represent a promising solution for meeting the stringent requirements of modern electronic systems in terms of compactness, efficiency, and high-performance filtering capabilities.

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